



Material Content Data Sheet



Sales Product Name		TLE82453SA		Issued		28. August 2013		
MA#		MA001139948						
Package		PG-DSO-36-54		Weight*		2111.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	22.403	1.06	1.06	10609	10609
leadframe	inorganic material	phosphorus	7723-14-0	0.388	0.02		184	
	non noble metal	zinc	7440-66-6	1.553	0.07		736	
	non noble metal	iron	7439-89-6	31.066	1.47		14712	
wire	non noble metal	copper	7440-50-8	1261.410	59.74	61.30	597376	613008
	non noble metal	copper	7440-50-8	7.370	0.35	0.35	3490	3490
	encapsulation	organic material	carbon black	1333-86-4	1.513	0.07		717
plastics		epoxy resin	-	69.616	3.30		32969	
	inorganic material	silicondioxide	60676-86-0	685.568	32.47	35.84	324670	358356
leadfinish	non noble metal	tin	7440-31-5	15.044	0.71	0.71	7124	7124
plating	noble metal	silver	7440-22-4	0.644	0.03	0.03	305	305
solder	noble metal	silver	7440-22-4	0.225	0.01		107	
	non noble metal	tin	7440-31-5	0.150	0.01		71	
	non noble metal	lead	7439-92-1	14.633	0.69	0.71	6930	7108
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

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